

# Product Change Notification / SYST-21CQR0460

# Date:

22-Sep-2022

# **Product Category:**

8-bit Microcontrollers

# PCN Type:

**Document Change** 

# **Notification Subject:**

ERRATA - PIC16(L)F18325/18345 Family Silicon Errata and Data Sheet Clarification

# **Affected CPNs:**

SYST-21CQRO460\_Affected\_CPN\_09222022.pdf SYST-21CQRO460\_Affected\_CPN\_09222022.csv

# **Notification Text:**

SYST-21CQRO460

Microchip has released a new Errata for the PIC16(L)F18325/18345 Family Silicon Errata and Data Sheet Clarification of devices. If you are using one of these devices please read the document located at PIC16(L)F18325/18345 Family Silicon Errata and Data Sheet Clarification.

Notification Status: Final

**Description of Change:** Updated Data Sheet Revision Letter.

Impacts to Data Sheet: None

Change Implementation Status: Complete

Date Document Changes Effective: 22 Sep 2022

NOTE: Please be advised that this is a change to the document only the product has not been changed.

Markings to Distinguish Revised from Unrevised Devices::N/A

# **Attachments:**

PIC16(L)F18325/18345 Family Silicon Errata and Data Sheet Clarification

Please contact your local Microchip sales office with questions or concerns regarding this notification.

### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile, including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. Affected Catalog Part Numbers (CPN)

PIC16F18345-E/6NVAO PIC16F18325-E/7NVAO PIC16F18325-E/P PIC16LF18325-E/P PIC16F18325-E/PREL PIC16F18325-E/SL PIC16LF18325-E/SL PIC16F18325-E/SLVAO PIC16F18325-E/ST PIC16LF18325-E/ST PIC16F18345-E/SS020 PIC16F18345-E/SS021 PIC16F18345-E/SS022 PIC16F18345-E/SS PIC16LF18345-E/SS PIC16F18345-E/SSVAO PIC16LF18345-E/SSVAO PIC16F18345-E/SO PIC16LF18345-E/SO PIC16F18345-E/P PIC16LF18345-E/P PIC16F18345-E/GZ PIC16LF18345-E/GZ PIC16LF18345-E/GZVAO PIC16F18325-E/JQ PIC16LF18325-E/JQ PIC16LF18325-E/JQVAO PIC16F18325-I/P PIC16LF18325-I/P PIC16F18325-I/SL PIC16LF18325-I/SL PIC16F18325-I/ST PIC16LF18325-I/ST PIC16F18325-I/STVAO PIC16F18345-I/SS PIC16LF18345-I/SS PIC16F18345-I/SO PIC16LF18345-I/SO PIC16F18345-I/P PIC16LF18345-I/P PIC16F18345-I/PREL PIC16F18345-I/GZ PIC16LF18345-I/GZ PIC16F18325-I/JQ PIC16LF18325-I/JQ PIC16F18325-I/JQVAO

PIC16F18345T-H/SS PIC16F18345T-H/SSV07 PIC16F18345T-H/SSVAO PIC16F18345-H/SS PIC16F18325T-I/SL PIC16LF18325T-I/SL PIC16F18325T-I/SLV05 PIC16F18325T-I/ST PIC16LF18325T-I/ST PIC16F18325T-I/STVAO PIC16F18345T-I/SS PIC16LF18345T-I/SS PIC16F18345T-I/SSVAO PIC16LF18345T-I/SSVAO PIC16F18345T-I/SO PIC16LF18345T-I/SO PIC16F18345T-I/GZ PIC16LF18345T-I/GZ PIC16F18325T-I/JQ PIC16LF18325T-I/JQ PIC16F18325T-I/JQVAO PIC16F18345T-E/6NV09 PIC16F18345T-E/6NVAO PIC16F18325T-E/7NVAO PIC16F18325T-E/SLV04 PIC16F18325T-E/SLVAO PIC16F18325T-E/STV06 PIC16F18325T-E/STVAO PIC16F18345T-E/SS020 PIC16F18345T-E/SS021 PIC16F18345T-E/SS022 PIC16F18345T-E/SS023 PIC16F18345T-E/SS024 PIC16F18345T-E/SS PIC16F18345T-E/SSV03 PIC16F18345T-E/SSV10 PIC16F18345T-E/SSV11 PIC16F18345T-E/SSVAO PIC16LF18345T-E/SSVAO PIC16F18345T-E/GZ PIC16LF18345T-E/GZ PIC16LF18345T-E/GZV01 PIC16LF18345T-E/GZV02 PIC16LF18345T-E/GZV08 PIC16LF18345T-E/GZVAO PIC16F18325T-E/JQ PIC16LF18325T-E/JQVAO



# PIC16(L)F18325/18345

# PIC16(L)F18325/18345 Family Silicon Errata and Data Sheet Clarification

The PIC16(L)F18325/18345 family devices that you have received conform functionally to the current Device Data Sheet (DS40001795**K**), except for the anomalies described in this document.

The silicon issues discussed in the following pages are for silicon revisions with the Device and Revision IDs listed in Table 1. The silicon issues are summarized in Table 2.

The errata described in this document will be addressed in future revisions of the PIC16(L)F18325/18345 silicon.

Note: This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated in the last column of Table 2 apply to the current silicon revision (A8).

Data Sheet clarifications and corrections start on page 6, following the discussion of silicon issues.

The silicon revision level can be identified using the current version of MPLAB<sup>®</sup> IDE and Microchip's programmers, debuggers, and emulation tools, which are available at the Microchip corporate website (www.microchip.com).

For example, to identify the silicon revision level using MPLAB IDE in conjunction with a hardware debugger:

- 1. Using the appropriate interface, connect the device to the hardware debugger.
- 2. Open an MPLAB IDE project.
- 3. Configure the MPLAB IDE project for the appropriate device and hardware debugger.
- For MPLAB X IDE, select <u>Window > Dashboard</u> and click the **Refresh Debug Tool Status** icon ( ).
- 5. Depending on the development tool used, the part number *and* Device Revision ID value appear in the **Output** window.

**Note:** If you are unable to extract the silicon revision level, please contact your local Microchip sales office for assistance.

The DEVREV values for the various PIC16(L)F18325/ 18345 silicon revisions are shown in Table 1.

Part Number	Device ID <sup>(1)</sup>	Re	Revision ID for Silicon Revision <sup>(2)</sup>							
Part Number	Device ID <sup>(*)</sup>	A4	A5	A7	A8					
DSTEMP	303Eh	2044h	2045h	2047h	2048h					
PIC16LF18325	3040h	2044h	2045h	2047h	2048h					
PIC16F18345	303Fh	2044h	2045h	2047h	2048h					
PIC16(L)F18325/18345	3041h	2044h	2045h	2047h	2048h					

 TABLE 1:
 SILICON DEVREV VALUES

**Note 1:** The Device IDs (DEVID and DEVREV) are located at addresses 8006h and 8005h, respectively. They are shown in hexadecimal in the format "DEVID DEVREV".

2: Refer to the "PIC16(L)F183XX Memory Programming Specification" (DS40001738) for detailed information on Device and Revision IDs for your specific device.

	E. d	ltem		Aff	ected R	evisior	ıs <sup>(1)</sup>
Module	Feature	Number	Issue Summary	A4	A5	A7	<b>A</b> 8
Oscillators	Fail-Safe Clock Monitor (FSCM)	1.1	The FSCM may fail to trigger.	Х	Х	Х	
Power-Saving Operation Modes	Sleep	2.1	Immediate wake-up after Sleep command may cause unstable code execution.	Х	Х		
Peripheral Pin Select (PPS)	PPSLOCK Unlock Sequence	3.1	PPS unlock sequence does not function while in DOZE.	Х	Х		
Nonvolatile Memory (NVM) Control	NVMREG Access	4.1	Self-writes on LF devices below 2.2V at -40°C or less may not work.	Х	X	X	
	WRERR Bit	4.2	Write Error (WRERR) bit is incorrectly set.	Х	X	Х	Х
Device Configuration	Revision ID	5.1	Bit 6 of the Revision ID is incorrectly set.	Х	X	Х	Х
Master Synchronous Serial Port (MSSP)	SPI Slave Mode	6.1	SSPBUF transmit shift register may be corrupted under certain conditions.	Х	X	X	
	I <sup>2</sup> C Communi- cation	6.2	Acknowledge failure on LF devices only.	Х	Х	Х	
Electrical Specifications	SMBus 2.0	7.1	The maximum VIL level changes when VDD is below 4.0V at 125°C.	Х	X	X	
	Fixed Voltage Reference (FVR) Accuracy	7.2	FVR output tolerance may be higher than specified at temperatures below -20°C.	Х	X	X	Х
	NVM Access	7.3	NVM access on LF devices may not work at all specified voltage and temperature ranges.	Х	X	X	Х
ADC Auto-Conversion Trigger	Auto-Conver- sion Trigger	8.1	Auto-trigger event does not begin a conversion while in Sleep.	Х	х	X	Х

### TABLE 2: SILICON ISSUE SUMMARY

Note 1: Only those issues indicated in the last column apply to the current silicon revision.

#### Silicon Errata Issues

**Note:** This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated by the shaded column in the following tables apply to the current silicon revision (**A8**).

#### 1. Module: Oscillators

#### 1.1 Fail-Safe Clock Monitor (FSCM)

The Fail-Safe Clock Monitor may fail to trigger with the loss of the external clock signal when the 4x PLL is enabled. This includes all external clock modes, LP, XT, HS, ECL, ECM and ECH.

#### Work around

None.

#### **Affected Silicon Revisions**

	<b>A</b> 4	A5	<b>A</b> 7	<b>A</b> 8		
ſ	Х	Х	Х			

#### 2. Module: Power-Saving Operation Modes

#### 2.1 Sleep Mode

When using the HFINTOSC as the system clock and the Sleep command is executed and the device immediately wakes up, the CPU will begin code execution at an unknown oscillator frequency until the oscillator stabilizes.

#### Work around

#### Method 1:

Use a peripheral that utilizes the HFINTOSC as a clock source or input to the peripheral. When a peripheral uses the HFINTOSC, the HFINTOSC will remain active during Sleep.

#### Method 2:

Before executing the Sleep command, switch the oscillator source to either the LFINTOSC or an external clocking source. Once the device wakes from Sleep, the HFINTOSC can be re-enabled as the primary oscillator source.

#### Method 3:

Enable the HFOEN bit in the OSCEN register. Setting this bit manually enables the HFINTOSC, and is unaffected by Sleep.

#### Affected Silicon Revisions

A4	A5	<b>A</b> 7	<b>A</b> 8		
Х	Х				

#### 3. Module: Peripheral Pin Select (PPS)

#### 3.1 PPS Unlock Sequence

When using the Peripheral Pin Select Unlock sequence while in DOZE mode, the unlock sequence is incorrectly executed, causing the sequence to fail and the PPS registers to remain locked.

#### Work around

The unlock sequence should not be performed while the device is in DOZE mode.

#### Affected Silicon Revisions

A4	A5	A7	<b>A</b> 8		
Х	Х				

#### 4. Module: Nonvolatile Memory (NVM) Control

#### 4.1 NVMREG Access

When performing self-writes through NVMREG access on PIC16LF18325/45 devices with VDD below 2.2V and a temperature of -40°C, the write operation may not work. This applies to both Program Flash Memory and EEPROM writes.

#### Work around

None.

#### Affected Silicon Revisions

<b>A</b> 4	A5	A7	<b>A</b> 8		
Х	Х	Х			

#### 4.2 NVM WRERR

If a Reset occurs while a self-write operation is in progress, the Write Error (WRERR) bit is set. If the user clears the WRERR bit and another Reset occurs even though no self-write is in progress, the WRERR bit will be incorrectly set again since the internal write latch has not been cleared.

#### Work around

A successful write operation will clear the WRERR condition.

#### Affected Silicon Revisions

A4	A5	<b>A</b> 7	<b>A</b> 8		
Х	Х	Х	Х		

#### 5. Module: Device Configuration

#### 5.1 Revision ID

When reading the Revision ID, bit 6 of the Revision ID register is incorrectly set, causing the Revision ID to read 204x (x = revision number) rather than 200x.

#### Work around

None.

#### Affected Silicon Revisions

A4	A5	A7	<b>A</b> 8		
Х	Х	Х	Х		

# 6. Module: Master Synchronous Serial Port (MSSP)

#### 6.1 MSSP SPI Slave Mode

When operating in SPI Slave mode, if the incoming SCK clock signal arrives during any of the conditions below, the SSPBUF transmit shift register may become corrupted. The transmitted slave byte cannot be assured to be correct, and the state of the WCOL bit may or may not indicate a write collision.

These conditions include:

- A write to an SFR
- A write to RAM following an SFR read
- A write to RAM prior to an SFR read.

#### Work around

Method 1 (Interrupt-based using SS):

Connect the  $\overline{SS}$  line to both the  $\overline{SS}$  input and either an INT or IOC input pin.

- 1. Enable INT or IOC interrupts (interrupt on falling edge if available, otherwise check that SS==0 when the interrupt occurs).
- 2. Load SSPBUF with the data to be transmitted.
- 3. Continue program execution.
- 4. When the Interrupt Service Routine (ISR) is invoked, do either of the following:
  - a) Add a delay that ensures the first SCK clock will be complete, or
  - b) Poll SSPSTAT.BF (while(BF==0)), and wait for the transmission/reception to complete.

Once one of these two methods are complete, it is safe to return to program execution.

Method 2 (Bit polling-based using SS):

- 1. Load SSPBUF with the data to be transmitted.
- 2. Poll the SS line and wait for the SS to go active (while(!PORTx.SS==0)).

- When SS is active (SS==0), do either of the following:
  - a) Add a delay that ensures the first SCK clock will be complete, or
  - b) Poll SSPSTAT.BF (while(BF==0)), and wait for the transmission/reception to complete.

Once one of these two methods are complete, it is safe to return to program execution.

Method 3 (SS not available):

- 1. Load SSPBUF with the data to be transmitted.
- Poll SSPSTAT.BF (while(BF==0)), and wait for the transmission/reception to complete.

#### Affected Silicon Revisions

<b>A</b> 4	A5	A7	<b>A</b> 8		
Х	Х	Х			

#### 6.2 I<sup>2</sup>C Communication

When using the MSSP on LF devices to perform  $I^2C$  communication, and the VDD voltage is above 3.0V, the Acknowledge (ACK) sequence does not always occur.

In 10-bit Slave mode, the MSSP may not generate the ACK sequence following reception of the second address byte (the lower address bits A7-A0). This issue occurs most commonly in 10-bit Slave mode. In 7-bit Slave mode, the MSSP may not generate the ACK sequence following the reception of the byte immediately following the 7-bit address (typically the first data byte).

In 10-bit Multi-Master mode, the MSSP may not generate the ACK sequence following the reception of the second address byte when acting as a slave. In 7-bit Multi-Master mode, the MSSP may not generate the ACK sequence following the reception of the first byte immediately following the 7-bit address when acting as a slave.

#### Work around

Do not exceed a VDD voltage of 3.0V when using an LF device for  $I^2C$  communications.

#### Affected Silicon Revisions

<b>A</b> 4	A5	A7	<b>A</b> 8		
Х	Х	Х			

#### 7. Module: Electrical Specifications

#### 7.1 SMBus 2.0 VIL Level

At 125°C, when the VDD voltage level supplied to the device is 4.0V and above, the maximum SMBus 2.0 voltage level for the VIL parameter is 0.8V. When VDD drops below 4.0V, the maximum SMBus voltage level for VIL drops to 0.7V. This issue applies to extended temperature devices only.

#### Work around

None.

A4	A5	<b>A</b> 7	<b>A</b> 8		
Х	Х	Х			

#### 7.2 Fixed Voltage Reference (FVR) Accuracy

At temperatures below -20°C, the output voltage for the FVR may be greater than the levels specified in the data sheet. This will apply to all three gain amplifier settings, (1X, 2X, 4X). The affected parameter numbers found in the data sheet are: FVR01 (1X gain setting), FVR02 (2X gain setting) and FVR03 (4X gain setting).

#### Work around

At temperatures above  $-20^{\circ}$ C, the stated tolerances in the data sheet remain in effect. Operate the FVR only at temperatures above  $-20^{\circ}$ C.

#### Affected Silicon Revisions

A4	A5	A7	<b>A</b> 8		
Х	Х	Х	Х		

#### 7.3 Nonvolatile Memory

Nonvolatile memory (NVM) access on LF devices may not work when operating at temperatures between -40°C and +25°C and VDD levels below 2.0V.

#### Work around

None.

#### Affected Silicon Revisions

A3	<b>A</b> 4	<b>A</b> 7	<b>A</b> 8		
Х	Х	Х	Х		

#### 8. Module: ADC Auto-Conversion Trigger

#### 8.1 ADC Auto-Conversion Trigger

When using ADC in Sleep mode, an autoconversion trigger event will not cause the ADC to begin a conversion.

#### Work around

None.

#### Affected Silicon Revisions

<b>A</b> 4	A5	A7	<b>A</b> 8		
Х	Х	Х	Х		

#### **Data Sheet Clarifications**

The following typographic corrections and clarifications are to be noted for the latest version of the device data sheet (DS40001795K):

Note:	Corrections are shown in <b>bold</b> . Where			
	possible, the original bold text formatting			
	has been removed for clarity.			

None.

### APPENDIX A: DOCUMENT REVISION HISTORY

#### Rev L Document (09/2022)

Updated Data Sheet Revision Letter.

#### Rev K Document (02/2019)

Updated Table 2. Fixed links.

Updated section 6.2 in Module 6: Master Synchronous Serial Port (MSSP).

Added section 7.3 in Module 7: Electrical Specifications.

Other minor corrections.

#### Rev J Document (03/2018)

Updated Table 1 and Table 2. Changes brought to Module 6: Master Synchronous Serial Port (MSSP).

Added Module 7: Electrical Specifications.

Added Module 8: ADC Auto-Conversion Trigger

Other minor corrections.

#### Rev H Document (07/2017)

Added Module 6 (Electrical Specifications); Updated Table 1 and 2; Other minor corrections.

#### Rev G Document (01/2017)

Silicon Errata issues:

Minor changes brought to Module 4: Nonvolatile Memory (NVM) Control, error temperature changed from  $0^{\circ}$  or less to  $-40^{\circ}$ C.

#### Rev F Document (01/2017)

Data Sheet Clarifications: Added Module 1: Comparator.

#### Rev E Document (10/2016)

Silicon Errata Issues: Added Module 5: Device Configuration.

#### Rev D Document (09/2016)

Silicon Errata Issues: Added Module 2: Power-Saving Operation Modes; Module 3: Peripheral Pin Select (PPS); Module 4: Nonvolatile Memory (NVM) Control.

Data Sheet Clarifications: Removed Modules 1-5. Data sheet has been updated.

#### Rev C Document (11/2015)

Added silicon revision A5.

#### Rev B Document (09/2015)

Data Sheet Clarifications:

Revised Module 2: Oscillators (modified Register 6-6); Added Module 4: Power-Saving Operation (modified Register 8.1); Added Module 5: Electrical Specifications (modified Table 34-11).

#### Rev A Document (09/2015)

Initial release of this document.

#### Note the following details of the code protection feature on Microchip products:

- Microchip products meet the specifications contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is secure when used in the intended manner, within operating specifications, and under normal conditions.
- Microchip values and aggressively protects its intellectual property rights. Attempts to breach the code protection features of Microchip product is strictly prohibited and may violate the Digital Millennium Copyright Act.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of its code. Code protection does not
  mean that we are guaranteeing the product is "unbreakable" Code protection is constantly evolving. Microchip is committed to
  continuously improving the code protection features of our products.

This publication and the information herein may be used only with Microchip products, including to design, test, and integrate Microchip products with your application. Use of this information in any other manner violates these terms. Information regarding device applications is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. Contact your local Microchip sales office for additional support or, obtain additional support at https:// www.microchip.com/en-us/support/design-help/client-supportservices.

THIS INFORMATION IS PROVIDED BY MICROCHIP "AS IS". MICROCHIP MAKES NO REPRESENTATIONS OR WAR-RANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION INCLUDING BUT NOT LIMITED TO ANY IMPLIED WARRANTIES OF NON-INFRINGEMENT, MERCHANTABILITY, AND FITNESS FOR A PARTICULAR PURPOSE, OR WARRANTIES RELATED TO ITS CONDITION, QUALITY, OR PERFORMANCE.

IN NO EVENT WILL MICROCHIP BE LIABLE FOR ANY INDI-RECT, SPECIAL, PUNITIVE, INCIDENTAL, OR CONSE-QUENTIAL LOSS, DAMAGE, COST, OR EXPENSE OF ANY KIND WHATSOEVER RELATED TO THE INFORMATION OR ITS USE, HOWEVER CAUSED, EVEN IF MICROCHIP HAS BEEN ADVISED OF THE POSSIBILITY OR THE DAMAGES ARE FORESEEABLE. TO THE FULLEST EXTENT ALLOWED BY LAW, MICROCHIP'S TOTAL LIABILITY ON ALL CLAIMS IN ANY WAY RELATED TO THE INFORMATION OR ITS USE WILL NOT EXCEED THE AMOUNT OF FEES, IF ANY, THAT YOU HAVE PAID DIRECTLY TO MICROCHIP FOR THE INFORMATION.

Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

#### Trademarks

The Microchip name and logo, the Microchip logo, Adaptec, AVR, AVR logo, AVR Freaks, BesTime, BitCloud, CryptoMemory, CryptoRF, dsPIC, flexPWR, HELDO, IGLOO, JukeBlox, KeeLoq, Kleer, LANCheck, LinkMD, maXStylus, maXTouch, MediaLB, megaAVR, Microsemi, Microsemi logo, MOST, MOST logo, MPLAB, OptoLyzer, PIC, picoPower, PICSTART, PIC32 logo, PolarFire, Prochip Designer, QTouch, SAM-BA, SenGenuity, SpyNIC, SST, SST Logo, SuperFlash, Symmetricom, SyncServer, Tachyon, TimeSource, tinyAVR, UNI/O, Vectron, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AgileSwitch, APT, ClockWorks, The Embedded Control Solutions Company, EtherSynch, Flashtec, Hyper Speed Control, HyperLight Load, Libero, motorBench, mTouch, Powermite 3, Precision Edge, ProASIC, ProASIC Plus, ProASIC Plus logo, Quiet-Wire, SmartFusion, SyncWorld, Temux, TimeCesium, TimeHub, TimePictra, TimeProvider, TrueTime, and ZL are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, Augmented Switching, BlueSky, BodyCom, Clockstudio, CodeGuard, CryptoAuthentication, CryptoAutomotive, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, Espresso T1S, EtherGREEN, GridTime, IdealBridge, In-Circuit Serial Programming, ICSP, INICnet, Intelligent Paralleling, IntelliMOS, Inter-Chip Connectivity, JitterBlocker, Knob-on-Display, KoD, maxCrypto, maxView, memBrain, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, PowerSmart, PureSilicon, QMatrix, REAL ICE, Ripple Blocker, RTAX, RTG4, SAM-ICE, Serial Quad I/O, simpleMAP, SimpliPHY, SmartBuffer, SmartHLS, SMART-I.S., storClad, SQI, SuperSwitcher, SuperSwitcher II, Switchtec, SynchroPHY, Total Endurance, Trusted Time, TSHARC, USBCheck, VariSense, VectorBlox, VeriPHY, ViewSpan, WiperLock, XpressConnect, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

The Adaptec logo, Frequency on Demand, Silicon Storage Technology, and Symmcom are registered trademarks of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2015-22, Microchip Technology Incorporated and its subsidiaries.

All Rights Reserved.

ISBN: 978-1-6683-1053-3

For information regarding Microchip's Quality Management Systems, please visit www.microchip.com/quality.



# **Worldwide Sales and Service**

#### AMERICAS

Corporate Office 2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support: http://www.microchip.com/ support

Web Address: www.microchip.com

Atlanta Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

Austin, TX Tel: 512-257-3370

**Boston** Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

**Chicago** Itasca, IL Tel: 630-285-0071 Fax: 630-285-0075

**Dallas** Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

**Detroit** Novi, MI Tel: 248-848-4000

Houston, TX Tel: 281-894-5983

Indianapolis Noblesville, IN Tel: 317-773-8323 Fax: 317-773-5453 Tel: 317-536-2380

Los Angeles Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608 Tel: 951-273-7800

Raleigh, NC Tel: 919-844-7510

New York, NY Tel: 631-435-6000

**San Jose, CA** Tel: 408-735-9110 Tel: 408-436-4270

**Canada - Toronto** Tel: 905-695-1980 Fax: 905-695-2078

#### ASIA/PACIFIC

Australia - Sydney Tel: 61-2-9868-6733

China - Beijing Tel: 86-10-8569-7000 China - Chengdu

Tel: 86-28-8665-5511 China - Chongqing Tel: 86-23-8980-9588

**China - Dongguan** Tel: 86-769-8702-9880

China - Guangzhou Tel: 86-20-8755-8029

China - Hangzhou Tel: 86-571-8792-8115

China - Hong Kong SAR Tel: 852-2943-5100

China - Nanjing Tel: 86-25-8473-2460

China - Qingdao Tel: 86-532-8502-7355

China - Shanghai Tel: 86-21-3326-8000

China - Shenyang Tel: 86-24-2334-2829

China - Shenzhen Tel: 86-755-8864-2200

China - Suzhou Tel: 86-186-6233-1526

**China - Wuhan** Tel: 86-27-5980-5300

China - Xian Tel: 86-29-8833-7252

China - Xiamen Tel: 86-592-2388138 China - Zhuhai

Tel: 86-756-3210040

#### ASIA/PACIFIC

India - Bangalore Tel: 91-80-3090-4444

India - New Delhi Tel: 91-11-4160-8631 India - Pune

Tel: 91-20-4121-0141 Japan - Osaka

Tel: 81-6-6152-7160 Japan - Tokyo

Tel: 81-3-6880- 3770 Korea - Daegu

Tel: 82-53-744-4301

Korea - Seoul Tel: 82-2-554-7200

Malaysia - Kuala Lumpur Tel: 60-3-7651-7906

Malaysia - Penang Tel: 60-4-227-8870

Philippines - Manila Tel: 63-2-634-9065

Singapore Tel: 65-6334-8870

Taiwan - Hsin Chu Tel: 886-3-577-8366

Taiwan - Kaohsiung Tel: 886-7-213-7830

Taiwan - Taipei Tel: 886-2-2508-8600

Thailand - Bangkok Tel: 66-2-694-1351

Vietnam - Ho Chi Minh Tel: 84-28-5448-2100

Tel: 31-416-690399 Fax: 31-416-690340

Italy - Milan

Italy - Padova

**EUROPE** 

Austria - Wels

Tel: 43-7242-2244-39

Tel: 45-4485-5910

Fax: 45-4485-2829

Tel: 358-9-4520-820

Tel: 33-1-69-53-63-20

Fax: 33-1-69-30-90-79

Germany - Garching

Tel: 49-2129-3766400

Germany - Heilbronn

Germany - Karlsruhe

Tel: 49-7131-72400

Tel: 49-721-625370

Germany - Munich

Tel: 49-89-627-144-0

Fax: 49-89-627-144-44

Germany - Rosenheim

Tel: 49-8031-354-560

Israel - Ra'anana

Tel: 972-9-744-7705

Tel: 39-0331-742611

Fax: 39-0331-466781

Tel: 39-049-7625286

**Netherlands - Drunen** 

Tel: 49-8931-9700

Germany - Haan

Finland - Espoo

France - Paris

Fax: 43-7242-2244-393

**Denmark - Copenhagen** 

Norway - Trondheim Tel: 47-7288-4388

Poland - Warsaw Tel: 48-22-3325737

Romania - Bucharest Tel: 40-21-407-87-50

**Spain - Madrid** Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

Sweden - Gothenberg Tel: 46-31-704-60-40

**Sweden - Stockholm** Tel: 46-8-5090-4654

**UK - Wokingham** Tel: 44-118-921-5800 Fax: 44-118-921-5820